

January 8, 2025

Asahi Diamond Industrial Co., Ltd. and Tokyo Seimitsu Co., Ltd.
Announcement of the Conclusion of MOU to Establish a Joint Venture

Asahi Diamond Industrial Co., Ltd. (hereinafter referred to as “Asahi Diamond”) and Tokyo Seimitsu Co., Ltd. (hereinafter referred to as “Tokyo Seimitsu”) have signed a memorandum of understanding (MOU) to establish a joint venture company to develop, manufacture and sell hub blades, one of the dicing blades used for dicing machines.

1. Purpose of Establishing a Joint Venture

Dicing blades used in dicing machines are classified into several types depending on their applications and materials, of which the largest market is for hub blades, which are mainly used for cutting silicon wafers. In order to provide customers with hub blades that meet their needs quickly, Asahi Diamond and Tokyo Seimitsu have reached a MOU to establish a joint venture company to develop, manufacture, and sell hub blades. Discussions and deliberations will proceed toward the conclusion of the joint venture agreement.

2. Outline of Joint Venture Company

Details of the joint venture company are under discussion between the two companies. The details of the joint venture company will be announced promptly after a formal decision is made.

3. Schedule

- Date of conclusion of the MOU to establish joint venture: January 8, 2025 (Wednesday)
- Date of conclusion of joint venture agreement: Within March 2025 (tentative)
- Date of establishment of joint venture: Within April 2025 (planned)
- Time of mass production and sales by the joint venture: Within FY2027 (planned)

4. Outlines of the Parties to the Basic Agreement

(1) Asahi Diamond Industrial Co., Ltd.

① Name of company	Asahi Diamond Industrial Co., Ltd.
② Head office location	4-1 Kioi-cho, Chiyoda-ku, Tokyo (New Otani Garden Court 11F)
③ Name and title of representative	Kazuki Kataoka, President and Representative Director
④ Major business lines	Manufacture, sale, and import/export of various tools, tools, and precision machinery for the application of diamonds and other hard materials, etc.

⑤ Capital stock	4.10 billion Yen (as of March 31, 2024)
⑥ Establishment	October 9 th , 1937

(2) Tokyo Seimitsu Co., Ltd.

① Name of company	Tokyo Seimitsu Co., Ltd.
② Head office location	2968-2, Ishikawa-machi, Hachioji-shi, Tokyo 192-8515, Japan
③ Name and title of representative	Ryuichi Kimura, President and COO
④ Major business lines	Sales and manufacture of semiconductor production equipment and measuring instruments
⑤ Capital stock	11.45 billion Yen (as of March 31, 2024)
⑥ Establishment	March 28 th , 1949

5. Prospects

Details of the joint venture company to be established are currently under discussion. We will promptly announce the details of the joint venture when they arise.